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[54] SEMICONDUCTOR ELEMENT MODULE
AND SEMICONDUCTOR DEVICE WHICH
PREVENTS SHORT CIRCUITING

[75] Inventors: Shinichi Takagi; Akinobu Suzuki,
both of Tokyo, Japan

[73] Assignee: Mitsubishi Denki Kabushiki Kaisha,
Tokyo, Japan

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Primary Examiner—Sheila V. Clark

Attorney, Agent, or Firm—Burns, Doane, Swecker & Mathis, LLP

[57] ABSTRACT

A semiconductor element module includes a package, a semiconductor element arranged on the package, and a plurality of leads provided on sides of the package so that an opening end of each the lead is oriented to the side of a package attaching plane, and serving to connect the semiconductor element to an external circuit; wherein a level differences is provided on the side of the package attaching plane of each of package sides so that a space is formed from each the plurality of leads.

10 Claims, 6 Drawing Sheets

